PATENT COOPERATION TREATY

PCT

REC'D 18 OCT 2005

PATENTABILITY POT

INTERNATIONAL PRELIMINARY REPORT ON PATENTA (Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference CH920030028	FOR FURTHER A	CTION	See Form PCT/IPEA/416		
International application No. PCT/IB2004/002724	International filing date 23.08.2004	(day/month/year)	Priority date (day/month/year) 29.09.2003		
International Patent Classification (IPC) or national classification and IPC H01L21/768, H01L21/027, G03F7/00					
Applicant INTERNATIONAL BUSINESS MACHINES CORPORATION					
 This report is the international preliminary examination report, established by this International Preliminary Examining Authority under Article 35 and transmitted to the applicant according to Article 36. 					
2. This REPORT consists of a total of 4 sheets, including this cover sheet.					
3. This report is also accompanied by	oy ANNEXES, comprisi	ng:	,		
a. 🗵 sent to the applicant and to the International Bureau) a total of 3 sheets, as follows:					
sheets of the description, claims and/or drawings which have been amended and are the basis of this report and/or sheets containing rectifications authorized by this Authority (see Rule 70.16 and Section 607 of the Administrative Instructions).					
sheets which supersede earlier sheets, but which this Authority considers contain an amendment that goes beyond the disclosure in the international application as filed, as indicated in item 4 of Box No. I and the Supplemental Box.					
	bles related thereto, in c	omputer readable form	er of electronic carrier(s)) , containing a nonly, as indicated in the Supplemental Instructions).		
4. This report contains indications re	elating to the following it	ems:			
☐ Box No. I Basis of the op	inion				
☐ Box No. II Priority					
☐ Box No. III Non-establishment of opinion with regard to novelty, inventive step and industrial applicability			step and industrial applicability		
☐ Box No. IV Lack of unity of	invention				
☐ Box No. VI Certain docume	ents cited				
☐ Box No. VII Certain defects	☐ Box No. VII Certain defects in the international application				
Date of submission of the demand		Date of completion of the	nis report		
28.07.2005		19.10.2005			
Name and mailing address of the international		Authorized Officer	ches Patoniem		
preliminary examining authority:	3as	Ploner, G	State of the state		
Tel. +31 70 340 - 2040 Tx: 31 651 epo nl Fax: +31 70 340 - 3016		Telephone No. +31 70	340-4225		

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No. PCT/IB2004/002724

			
	Box No.	Basis of the report	
1.	With regard to the language , this report is based on the international application in the language in which it was filed, unless otherwise indicated under this item.		
	☐ This which	report is based on translations from the original language into the following language , i is the language of a translation furnished for the purposes of:	
		ernational search (under Rules 12.3 and 23.1(b))	
		iblication of the international application (under Rule 12.4) Pernational preliminary examination (under Rules 55.2 and/or 55.3)	
2.	With regard to the elements * of the international application, this report is based on <i>(replacement sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to in this report as "originally filed" and are not annexed to this report):</i>		
	Descriptio	n. Pages	
	_	as originally filed	
	1-16	as originally filed	
,	Claims, N	umbers	
	1-13	received on 02.08.2005 with letter of 28.07.2005	
	Drawings, Sheets		
	1/4-4/4	as originally filed	
	□ a sec	uence listing and/or any related table(s) - see Supplemental Box Relating to Sequence Listing	
3. The amendments have resulted in the cancellation of:		mendments have resulted in the cancellation of:	
		e description, pages	
		e claims, Nos.	
		e drawings, sheets/figs e sequence listing <i>(specify)</i> :	
		ny table(s) related to sequence listing <i>(specify)</i> :	
4.	had not b	report has been established as if (some of) the amendments annexed to this report and listed below seen made, since they have been considered to go beyond the disclosure as filed, as indicated in the ental Box (Rule 70.2(c)).	
		e description, pages	
		e claims, Nos.	
		e drawings, sheets/figs e sequence listing <i>(specify)</i> :	
		ny_table(s) related to_sequence_listing_(specify):	
	* If i	tem 4 applies, some or all of these sheets may be marked "superseded."	

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No. PCT/IB2004/002724

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

1. Statement

Novelty (N)

Yes: Claims

1-13

No: Claims

Inventive step (IS)

Yes: Claims

1-13

No: Claims

Industrial applicability (IA)

Yes: Claims

1-13

No: Claims

2. Citations and explanations (Rule 70.7):

see separate sheet

Re Item V

Reasoned statement with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

Reference is made to the following document:

D1: US-B1-6 517 995 (Jacobson et al.); 11 February 2003 (2003-02-11)

1.

Claim 1 lacks clarity (Article 6 PCT). In claim 1, the phrase "wherein the aligning comprises stretching the stamp" is considered to be vague in that it does not specify the direction of said "stretching".

In the following assessment of novelty and inventive step it is therefore assumed that said "stretching the stamp" is a lateral stretching resulting from offsetting said protrusions and recesses in said stamp and surface, respectively.

2.

The document D1 discloses a method of forming a multilevel structure by pressing a patterned elastomeric stamp into a curable liquid layer deposited on a surface.

The subject-matter of claim 1 differs from this known method mainly in that the aligning of the elastomeric stamp comprises stretching the stamp.

The document D1 neither discloses nor suggests said step of stretching the stamp during alignment. Consequently, the subject-matter of claim 1 is considered to meet the requirements of Article 33(1) PCT in respect of novelty (Article 33(2) PCT) and inventive step (Article 33(3) PCT).

3.

Claims 2-13 are dependent on claim 1 and as such also meet the requirements of the PCT with respect to novelty and inventive step.

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Revised CLAIMS

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A method for forming a multilevel structure on a surface (100), the method comprising: depositing a curable
 liquid layer (180; 200) on the surface; pressing a stamp (120) formed from an elastomeric material and having a multilevel pattern (121, 122) therein into the liquid layer to produce in the liquid layer a multilevel structure defined by the pattern; and, curing the liquid layer to produce a solid layer
 having the multilevel structure therein,

the method further comprising, prior to the pressing, aligning the stamp relative to the surface via complementary formations on the stamp and the surface, wherein the aligning comprises lubricating movement of the stamp relative to the

15 surface via the liquid layer and wherein the complementary formations comprise protrusions (310, 320) on one of the stamp and the surface and recesses (330, 340) for receiving the protrusions on the other of the stamp and the surface;

wherein the aligning comprises stretching the stamp.

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- 2. A method as claimed in claim 1, wherein the protrusions are offset (d) relative to the corresponding recesses to produce the deformation of the stamp.
- 25 3. A method as claimed in claim 1 or 2, wherein the depositing comprises depositing an excess of the liquid comprising the liquid layer on the protrusions.
 - 4. A method as claimed in claim 3, wherein the aligning
- 30 comprises expansion of the recesses in the direction of the offset when brought into contact with corresponding protrusions, the elasticity of the stamp providing an exit path for the excess liquid and allowing each recess to close around a corresponding protrusion.

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5. A method as claimed in any preceding claim, wherein the solid layer is formed from a dielectric material (200) and the multilevel structure comprises a multilevel cavity (195) in the solid layer.

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- 6. A method as claimed in any one of claims 1 to 4, wherein the solid layer is formed from a resist material (180), the multilevel structure comprises a multilevel cavity (195) in the solid layer, and the depositing comprises 10 depositing the resist material in liquid form on a dielectric layer (140, 160).
- 7. A method as claimed in claim 6, comprising etching the dielectric layer via the solid layer to transfer the cavity
 15 from the solid layer to the dielectric layer.
 - 8. A method as claimed in any one of claims 5, 6 or 7, comprising depositing metal (190) in the cavity to produce a conductive structure embedded in dielectric material.

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- 9. A method as claimed in claim 8, comprising performing thiol printing on the dielectric layer, thereby to prevent deposition of the metal outside the cavity.
- 25 10. A method as claimed in any one of claims 5 to 9, wherein the cavity comprises a first level (121) corresponding to a longitudinal element of the conductive structure and a second level (122) corresponding to a lateral element of the conductive structure.

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11. A method as claimed in claim 10, wherein the longitudinal element comprises a via for completing an electrical connection between adjacent levels of a multilevel interconnection structure for an integrated circuit, and the

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lateral element comprises a wire for completing an electrical connection within one of the adjacent levels of the integrated circuit.

- 5 12. A method as claimed in any preceding claim, wherein the curing comprises exposing the liquid layer to ultra violet light via the stamp.
- 13. A method for fabricating an integrated circuit having a 10 multilevel interconnection structure, the method comprising, between at least one pair of adjacent levels of the interconnection structure, forming an electrically conductive structure by performing a method as claimed in claim 11.

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